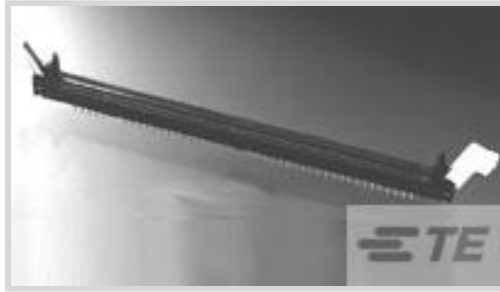




Connectors > Socket Connectors > Memory Sockets > DIMM Sockets



DRAM Type: **Double Data Rate (DDR) 2**

Connector System: **Board-to-Board**

Number of Positions: **240**

Termination Method to PCB: **Surface Mount**

Module Orientation: **Vertical**

## Features

### Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 2
Connector System	Board-to-Board

### Configuration Features

Number of Bays	2
Number of Keys	1
Number of Rows	2
Number of Positions	240
Module Orientation	Vertical

### Body Features

Ejector Location	Both Ends
Latch Material	Thermoplastic
Retention Post Location	None
Ejector Material	Thermoplastic
Module Key Type	Offset Right
Ejector Type	Standard

### Contact Features

Memory Socket Type	Memory Card
Socket Style	DIMM
Contact Mating Area Plating Material Thickness	.05 – .75 $\mu$ m[2 $\mu$ in]



Contact Mating Area Plating Material	Gold
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PCB Contact Termination Area Plating Material	Tin
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Contact Base Material	Copper Alloy
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Contact Current Rating (Max)	.5 A
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### Termination Features

Insertion Style	Direct Insert
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Termination Method to PCB	Surface Mount
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### Mechanical Attachment

Mount Angle	Right Angle
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PCB Mount Alignment Type	Locating Posts
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Mating Alignment Type	None
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PCB Mount Retention	With
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PCB Mount Retention Type	Solder Peg
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Connector Mounting Type	Board Mount
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### Housing Features

Housing Material	Thermoplastic
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Housing Color	Black
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Centerline (Pitch)	1 mm [.039 in]
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### Dimensions

Profile Height from PCB	6.8 mm [.26 in]
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Row-to-Row Spacing	6.3 mm [.248 in]
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### Usage Conditions

Operating Temperature Range	-55 – 85 °C [-67 – 185 °F]
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### Operation/Application

Circuit Application	Signal
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### Industry Standards

UL Flammability Rating	UL 94V-0
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### Packaging Features

Packaging Quantity	16
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Packaging Method	Box & Tray, Tray
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### Product Compliance






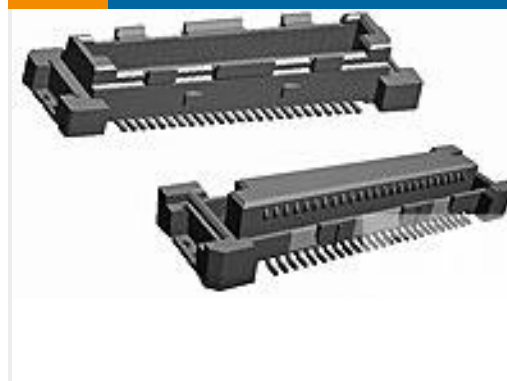
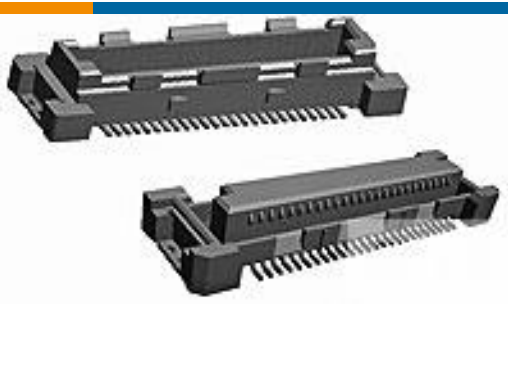



[For compliance documentation, visit the product page on TE.com>](#)

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 245°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

## Customers Also Bought

 <p>TE Part #2176403-2 3550 1R1 1%</p>	 <p>TE Part #2176406-9 3560 2R2 1%</p>	 <p>TE Part #NB18922001 RNF-100-1/16-YO-STK</p>	 <p>TE Part #1-5353727-0 .6FHP08H,280,B,GIG,08/Sn,ST,NSYes</p>
 <p>TE Part #1-5353729-0 .6FHR04H,280,B,GIG,08/Sn,ST,NSYes</p>	 <p>TE Part #2118721-4 STD SHIELD COVER, AL-38.60X25.90X2.00MM</p>	 <p>TE Part #2085958-1 ICCON,SIZE 4,LOCKING PIN ASSEMBLY</p>	 <p>TE Part #5-535512-2 112 MODII HORZ DR CE EESS .100</p>



## Documents

### Product Drawings

[DDR 2 SMT ASS'Y 240P \(WITH BOS](#)

English

### CAD Files

Customer View Model

[ENG\\_CVM\\_CVM\\_1939495-1\\_K.2d\\_dxf.zip](#)

English

3D PDF

3D

Customer View Model

[ENG\\_CVM\\_CVM\\_1939495-1\\_K.3d\\_igs.zip](#)

English

Customer View Model

[ENG\\_CVM\\_CVM\\_1939495-1\\_K.3d\\_stp.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

### Product Specifications

[DDR-II DIMM Socket 240 Positions SMT Type](#)

Japanese

[Product Specification](#)

Japanese